

CLAIMS

What is claimed is:

1. A drive cooling baffle, comprising:
 - a main body portion defining and extending between an inlet opening and an outlet opening, at least one of the openings is configured to cooperate with a fan to cool at least one electronics component, the main body portion being configured to generally enclose the at least one electronics component; and
 - hook and loop material secured to an interior surface of the main body portion, the hook and loop material being configured and disposed to engage with corresponding hook and loop material secured to at least one of the fan and the electronics component.
2. The drive cooling baffle of claim 1, further comprising a flange configured to be in contact with an electronics component base to which the drive cooling baffle, the fan, and the electronics component are attached, the flange being further configured to engage with a hold down tab defined in the electronics components base.
3. The drive cooling baffle of claim 1, wherein the main body portion is made of a conductive plastic material.
4. The drive cooling baffle of claim 1, wherein the interior surface of the main body portion has a conductive coating thereon.

5. The drive cooling baffle of claim 1, wherein the main body portion further defines an opening configured to allow cabling associated with the at least one electronics component to pass therethrough.

6. The drive cooling baffle of claim 1, wherein the main body portion further 5 defines at least one indentation on the interior surface thereof to receive the hook and loop material.

7. A drive cooling system, comprising:
an inflow fan;
an outflow fan;
10 a drive cooling baffle extending generally between the inflow fan and the outflow fan, the baffle being configured to generally enclose at least one electronics component to be cooled.

8. The drive cooling system of claim 7, wherein the inflow fan is configured to generate greater air movement than the outflow fan.

15 9. The drive cooling system of claim 7, wherein the drive cooling baffle further includes hook and loop material secured to an interior surface thereof, the hook and loop material being configured and disposed to engage with corresponding hook and loop material secured to at least one of the fans and the electronics component.

10. The drive cooling system of claim 9, wherein the drive cooling baffle further defines at least one indentation on the interior surface thereof to receive the hook and loop material.

11. The drive cooling system of claim 7, wherein the baffle further includes a
5 flange configured to be in contact with an electronics components base to which the baffle, the fan, and the electronics component are attached, the flange being further configured to engage with a hold down tab defined in the electronics components base.

12. The drive cooling system of claim 7, wherein the baffle is made of a conductive plastic material.

10 13. The drive cooling system of claim 7, wherein the interior surface of the baffle has a conductive coating thereon.

14. The drive cooling system of claim 7, wherein the baffle further defines an opening configured to allow cabling associated with the at least one electronics component to pass therethrough.

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